

EpoxyLite

Technical Data Sheet

Product: EpoxyLite EIP 5652

Description: Two component, unfilled Epoxy resin suitable for use at Class H temperatures.

EpoxyLite EIP 5652 has a low viscosity for optimum flow and penetration of wound components and cures, with a low exotherm in large bulk, to produce a tough resilient product.

Application: Encapsulating and potting of components which require excellent thermal cycling characteristics in service.

Processing Characteristics:

	Resin	Hardener	Mixture	
Viscosity	3500	20	500	mPas @ 25°C
Specific Gravity	1.14	0.96	1.10	g / cm³
Mix Ratio	Resin to Hardener 4 : 1			p.b.w.
Mix Ratio	Resin to Hardener 3.5 : 1			p.b.v.
Gelation Time	90 minutes			@ 50°C
Cure Schedule	48 hours			@ 25°C
	or 6 hours			@ 80°C

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Cured Properties:

Shore D Hardness:	(DIN 53505)	80 (25°C)
Thermal Class:	(ASTM D2307 / 20000 hrs)	180°C
Glass Transition Temp.	(IEC 1006)	62°C
Tensile Strength:	(ISO 527)	60 N/mm²
Elongation at Break:	(ISO 527)	1.2 %
Thermal Coefficient of Expansion:	(DIN 53752)	75.10⁻⁶K⁻¹
Thermal Conductivity:	(ISO 8894-1)	0.23 W/mK
UL Recognition:	(UL94)	-
Water Absorption:	(ISO 62)	0.15 % (23°C)
Dielectric Strength:	(IEC 243-1)	190 kV/cm
Dielectric Constant:	(IEC 250)	5.2 @ 50 Hz
Dissipation Factor:	(IEC 250)	10% @ 50 Hz
Volume Resistivity:	(IEC 93)	> 10¹³ ohm/cm
Comparative Tracking Index:	(IEC 112)	> 550 Volts

Storage: Minimum storage life 12 months in tightly closed containers at temperatures below 25°C.

Handling: Refer Material Safety Data Sheet.

Issue: 04/01/2005

This information is based on test results believed to be accurate and reliable. Nothing herein however, is to be considered a warranty, either expressed or implied regarding the application and performance of EpoxyLite materials, since the conditions of use are beyond our control.